

Method of Resin-Seal-Molding Electronic Component and Apparatus therefor

ABSTRACT OF THE DISCLOSURE

A mold (110) for resin-seal-molding an electronic component is constituted by a first mold (111) and a second mold (112). A plurality of mold structure units (molds 110) are arranged as stacked, wherein a substrate supplying portion (substrate supply-set surface 113) for supplying a single before-resin-seal-molding substrate (400) having an electronic component mounted thereon is provided at a mold face (PL) of the molds. Further, a clamp mechanism (press frame mechanism 130) for simultaneously applying clamping pressure to each of the plurality of mold structure units (molds 110) arranged as stacked. With this structure, the overall structure of the mold (110) for resin-seal-molding an electronic component mounted on the substrate (400) can be simplified. Additionally, resin flash formation on the substrate surface due to variation in the thicknesses of the substrates (400) when resin-seal-molding the electronic component is prevented.

Fig 7